

AN-1280 LM2731/LM2733 Evaluation Board

1 Introduction

The LM2731 and LM2733 are high frequency switching boost regulators that offer small size and high power conversion efficiency. The "X" version of the part operates at 1.6MHz switching frequency and the "Y" version at 600kHz. The primary difference between the LM2731 and LM2733 is that the LM2731 has a higher current internal switch FET (with lower breakdown voltage), while the LM2733 has a higher voltage FET that handles less current. The LM2733 targets applications with higher output voltages, while the LM2731 is intended for applications requiring higher load currents at lower output voltages. This user's guide will describe the evaluation board supplied to demonstrate the operation of these parts and give information on its usage.

2 Basic Application Circuit

The basic application circuit shown in Figure 1 provides the component designators used on the evaluation board.



Figure 1. Evaluation Board Basic Application Circuit

All trademarks are the property of their respective owners.



Component Layout

3 Component Layout



Figure 2. Evaluation Board Component Layout



4 **Basic Application Circuit - LM2733Y**

Designation	Description	Size	Manufacturer Part #	Vendor
C1	Cap 2.2µF 16V	1206	EMK316BJ225ML	Taiyo Yuden
C2	Cap 4.7µF 16V	1812	EMK432BJ475ML	Taiyo Yuden
C3	Cap 220pF 50V	0805	VJ0805A221JXACW1BC	Vishay
R1	RES, 51k Ohm, 5%, 0.1W	0805	CRCW080551K0JNEA	Vishay
R2	RES, 118k Ohm, 1%, 0.1W	0805	CRCW0805118KFKEA	Vishay
R3	RES, 13.3k Ohm, 1%, 0.1W	0805	CRCW080513K3FKEA	Vishay
L1	Shielded Inductor 10µH 4A		CDRH125-100MC	Sumida
D1	Diode 20V 0.5A	SOT23	MBR0520	International Rectifier
U1	IC LM2733YMF			Texas Instrumen

Table 1. LM2733Y Bill of Materials ($V_{IN} = 5V$, $V_{OUT} = 12V$, $I_{OUT} = 250$ mA)



TIME (10 ms/DIV) Figure 3. Start Up $V_{IN} = 5V, V_{OUT} = 12V, I_{OUT} = 250mA$







Figure 4. Switching Waveform and Output Voltage Ripple $V_{IN} = 5V, V_{OUT} = 12V, I_{OUT} = 250mA$





5 Basic Application Circuit - LM2733X

Designation	Description	Size	Manufacturer Part #	Vendor
C1	Cap 2.2µF 16V	1206	EMK316BJ225ML	Taiyo Yuden
C2	Cap 4.7µF 16V	1812	EMK432BJ475ML	Taiyo Yuden
C3	Cap 220pF 50V	0805	VJ0805A221JXACW1BC	Vishay
R1	RES, 51k Ohm, 5%, 0.1W	0805	CRCW080551K0JNEA	Vishay
R2	RES, 118k Ohm, 1%, 0.1W	0805	CRCW0805118KFKEA	Vishay
R3	RES, 13.3k Ohm, 1%, 0.1W	0805	CRCW080513K3FKEA	Vishay
L1	Shielded Inductor 10µH 4A		CDRH125-100MC	Sumida
D1	Diode 20V 0.5A	SOT23	MBR0520	International Rectifier
U1	IC LM2733XMF			Texas Instrumen

Table 2. LM2733X Bill of Materials ($V_{IN} = 5V$, $V_{OUT} = 12V$, $I_{OUT} = 250$ mA)



Figure 7. Start Up V_{IN} = 5V, V_{OUT} = 12V, I_{OUT} = 250mA



Figure 9. Load Transient $V_{IN} = 5V, V_{OUT} = 12V, I_{OUT} = 50mA$ to 200mA



Figure 8. Switching Waveform and Output Voltage Ripple $V_{IN} = 5V, V_{OUT} = 12V, I_{OUT} = 250mA$





6 Basic Application Circuit - LM2731Y

Designation	Description	Size	Manufacturer Part #	Vendor
C1	Cap 2.2µF 16V	1206	EMK316BJ225ML	Taiyo Yuden
C2	Cap 22µF 16V	1812	EMK432BJ226ML	Taiyo Yuden
C3	Cap 470pF 50V	0805	VJ0805A471JXAMX	Vishay
R1	RES, 51k Ohm, 5%, 0.1W	0805	CRCW080551K0JNEA	Vishay
R2	RES, 40.2k Ohm, 1%, 0.1W	0805	CRCW08054022F	Vishay
R3	RES, 13.3k Ohm, 1%, 0.1W	0805	CRCW080513K3FKEA	Vishay
L1	Shielded Inductor 4.7µH 1.68A		NRS6012T6R8MMGJ	Taiyo Yuden
D1	Diode 20V 0.5A	SOT23	MBR0520	International Rectifier
U1	IC LM2731YMF			Texas Instrumen





Figure 11. Start Up V_{IN} = 3.3V, V_{OUT} = 5V, I_{OUT} = 500mA



Figure 13. Load Transient $V_{\mbox{\tiny IN}}$ = 3.3V, $V_{\mbox{\tiny OUT}}$ = 5V, $I_{\mbox{\tiny OUT}}$ = 200mA to 400mA



Figure 12. Switching Waveform and Output Voltage Ripple V_{IN} = 3.3V, V_{OUT} = 5V, I_{OUT} = 500mA



7 Basic Application Circuit - LM2731X

Designation	Description	Size	Manufacturer Part #	Vendor
C1	Cap 2.2µF 16V	1206	EMK316BJ225ML	Taiyo Yuden
C2	Cap 4.7µF 16V	1812	EMK432BJ475ML	Taiyo Yuden
C3	Cap 220pF 50V	0805	VJ0805A221JXACW1BC	Vishay
R1	RES, 51k Ohm, 5%, 0.1W	0805	CRCW080551K0JNEA	Vishay
R2	RES, 118k Ohm, 1%, 0.1W	0805	CRCW0805118KFKEA	Vishay
R3	RES, 13.3k Ohm, 1%, 0.1W	0805	CRCW080513K3FKEA	Vishay
L1	Shielded Inductor 10µH 4A		CDH53-4R7MC	Sumida
D1	Diode 20V 0.5A	SOT23	MBR0520	International Rectifier
U1	IC LM2731XMF			Texas Instrumen

Table 4. LM2731XBill of Materials ($V_{IN} = 5V$, $V_{OUT} = 12V$, $I_{OUT} = 500$ mA



Figure 15. Start Up V_{IN}=5V, V_{OUT}=12V, I_{OUT}=500mA



Figure 17. Load Transient V_{IN} =5V, V_{OUT} =12V, I_{OUT} = 200mA to 400mA



Figure 16. Switching Waveform and Output Voltage Ripple V_{IN}=5V, V_{out}=12V, I_{out}=500mA





(1)

(2)

(3)

8 Adjusting the Output Voltage

The output voltage is set using R2 and R3 as given by the formula:

V_{OUT} = 1.23 (R2/R3) + 1.23

Solved for R2:

 $R2 = (V_{OUT} - 1.23) / 1.23 \times R3$

The evaluation board as shipped has a 13.3k resistor installed at R3. The appropriate value for R2 for any output may be calculated from the above formula.

9 Feedforward Compensation

The feedforward capacitor C3 should be selected to set the compensation zero at approximately 8 kHz. The value of C3 is calculated using:

 $C3 = 1 / (2 \times \pi \times 8k \times R2)$

The value of C3 is calculated after R2 is selected for the output voltage needed for the specific application.

10 Guidelines for Component Selection

Since it is assumed that some of the eval boards will be modified to be used in different voltage and current configurations, some guidelines are given to help select components which are likely to be changed.

INDUCTOR L1: The amount of inductance required depends on switching frequency, duty cycle and amount of allowable ripple current. 10 μ H is a good choice for most applications. At low boost ratios such as 3.3V to 5V, the LM2731 loop stability requires that the inductance not exceed 6.8 μ H. Smaller inductors may be used in applications with less output current. Higher ripple current resulting from a smaller inductor means the maximum average current (and power) will be less. Duty cycle also affects ripple current, since the time the switch is ON determines the length of time that the current has to ramp up. Any design must be verified for maximum load current over the full temperature range of the application to make sure the inductance is sufficient.

Smaller inductors can be used (and make more sense economically) if the load current is fairly light. The part may operate in discontinuous mode (where inductor current drops to zero during each switching cycle) using less inductance, but this is harmless and actually increases stability (phase margin) compared to continuous operation.

DIODE D1: Because of the fast switching speeds, a Schottky diode must be used for D1. The voltage rating (minimum) should be at least 5V higher than the output voltage for safe design margin. The average current rating of the diode should be at least 50% more than the maximum output load current of the application.

OUTPUT CAPACITOR C2: The output capacitor(s) used on the LM273X must be good quality ceramics of the X7R or X5R type. Z5U or Z5F types will not give sufficient capacitance because of the applied voltage reducing effective capacitance.

The output capacitor is also critical for stability. As a basic guideline, it is recommended for the LM2733: 4.7 μ F minimum, at output voltages of 10V or above. At lower output voltages, use 10-22 μ F. In general, the higher the load current, the more output capacitance is required for stability. For the LM2731: use at least 10 μ F in 5V to 12V applications, and use 22 μ F at lower boost ratios (such as 3.3 to 5V).

Stability of the specific application should be verified over the full operating temperature range by load step testing, where the load current is increased from no load to full load abruptly. This can be done simply by tapping the lead from the load box onto the output terminal. The amount of ringing seen on the output voltage waveform will define the stability of the design.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications		
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive	
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications	
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers	
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps	
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy	
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial	
Interface	interface.ti.com	Medical	www.ti.com/medical	
Logic	logic.ti.com	Security	www.ti.com/security	
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense	
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video	
RFID	www.ti-rfid.com			
OMAP Applications Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com	
Wireless Connectivity	www.ti.com/wirelessconnectivity			

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2013, Texas Instruments Incorporated